

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Operating Supply Voltage	V <sub>P</sub> - V <sub>N</sub>	6.0	V	-
DC Voltage at any Channel Input	-	(V <sub>N</sub> - 0.5) to (V <sub>P</sub> + 0.5)	V	-
Peak Pulse Current	I <sub>PP</sub>	5.0	A	8/20μs, Per Fig. 3
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±8	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±15	kV	Standard IEC 61000-4-2

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	380	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	327	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Operating Supply Voltage	V <sub>P</sub>	-	3.3	5.5	V	-
Operating Supply Current (Note 6)	I <sub>P</sub>	-	-	8.0	μA	(V <sub>P</sub> - V <sub>N</sub> ) = 3.3V
Channel Leakage Current (Note 6)	I <sub>R</sub>	-	0.1	1.0	μA	V <sub>P</sub> = 5V, V <sub>N</sub> = 0V
Reverse breakdown voltage	V <sub>BR</sub>	6.0	-	-	V	I <sub>R</sub> = 1mA
Clamping Voltage, Positive Transients	V <sub>CL1</sub>	-	10.0	-	V	I <sub>PP</sub> = 1A (Note 7)
Clamping Voltage, Negative Transients	V <sub>CL2</sub>	-	-1.7	-	V	I <sub>PP</sub> = -1A (Note 7)
Forward Voltage for Top Diode	V <sub>FD1</sub>	0.60	0.80	0.95	V	I <sub>F</sub> = 8mA, any channel to V <sub>P</sub>
Forward Voltage for Bottom Diode	V <sub>FD2</sub>	0.60	0.80	0.95	V	I <sub>F</sub> = 8mA, V <sub>N</sub> to and channel
Dynamic Resistance	R <sub>DYN</sub>	-	0.9	-	Ω	I <sub>PP</sub> = 1A (Note 7)
Channel Input Capacitance	C <sub>T</sub>	-	0.85	1.2	pF	V <sub>IN</sub> = 1.65V, V <sub>P</sub> = 3.3V, V <sub>N</sub> = 0V, f = 1MHz

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
  6. Short duration pulse test used to minimize self-heating effect.
  7. Clamping voltage value is based on an 8x20μs peak pulse current (I<sub>PP</sub>) waveform.
  8. Measured from any channel to V<sub>N</sub>.
  9. Measured from V<sub>P</sub> to V<sub>N</sub>.
  10. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: [http://www.diodes.com/destdtools/appnote\\_dnote.html](http://www.diodes.com/destdtools/appnote_dnote.html).

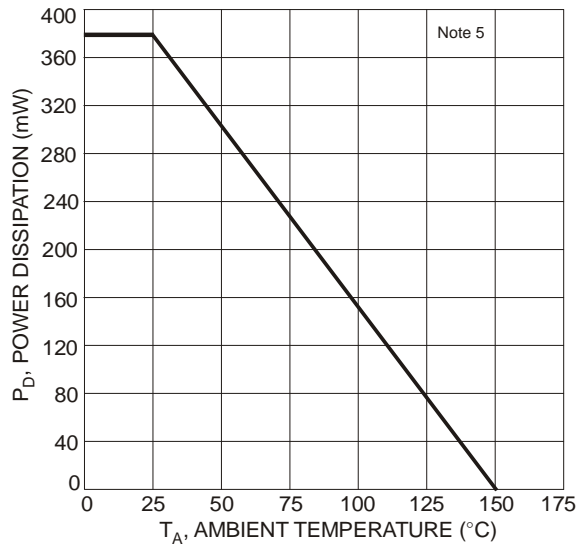


Figure 1 Power Derating Curve

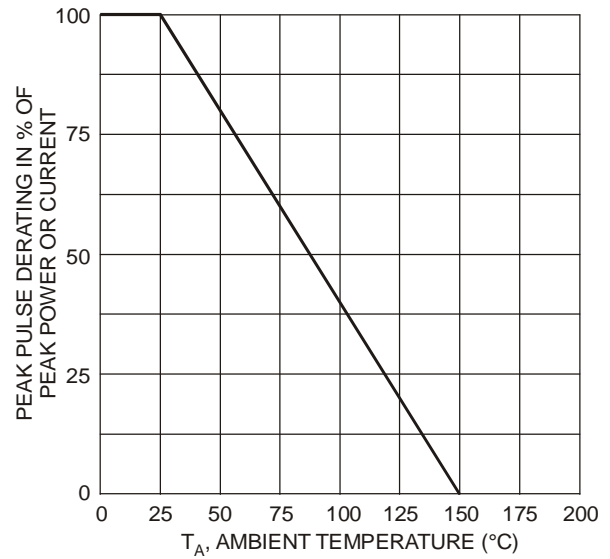


Figure 2 Pulse Derating Curve

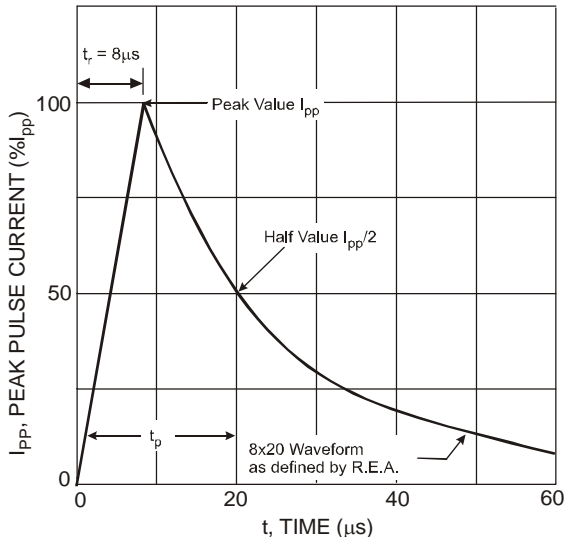


Figure 3 Pulse Waveform

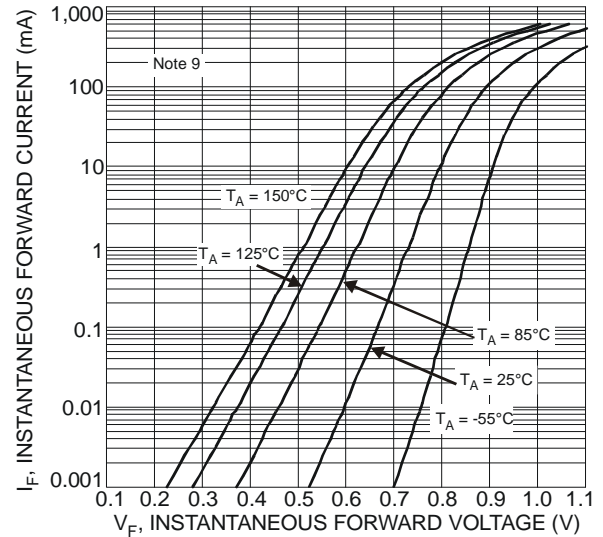


Figure 4 Typical Forward Characteristics

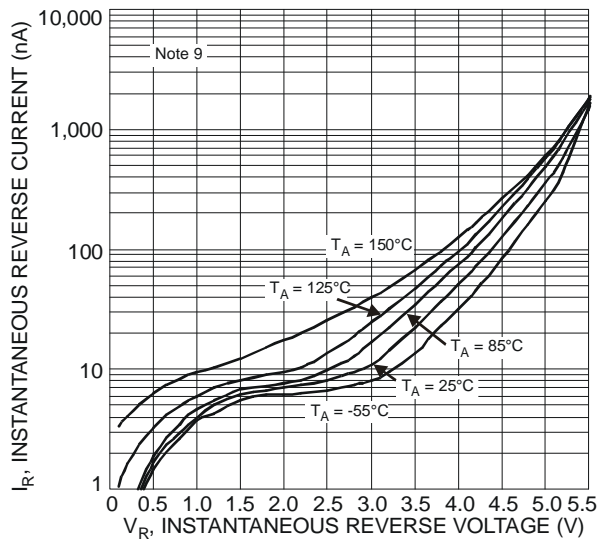


Figure 5 Typical Reverse Characteristics

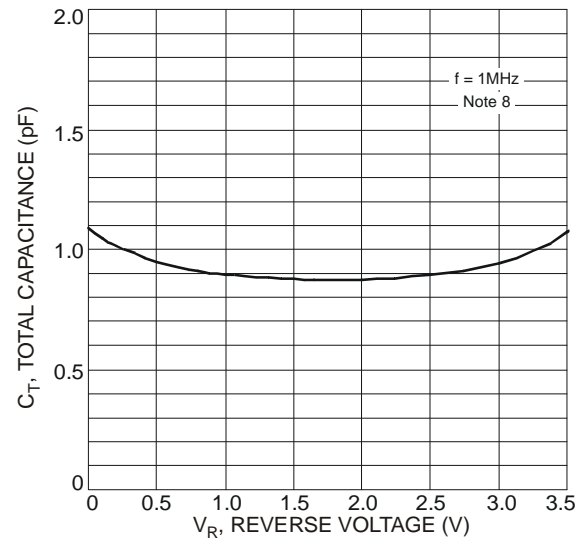
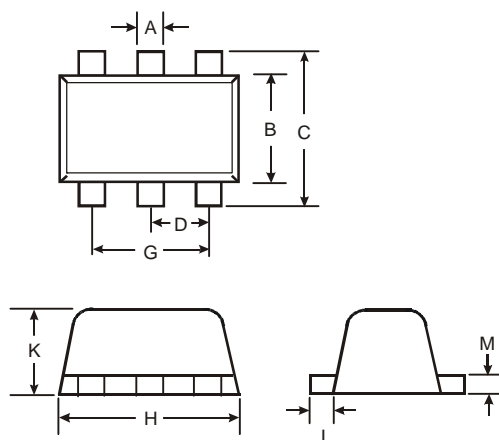


Figure 6 Typical Total Capacitance vs. Reverse Voltage

## Package Outline Dimensions

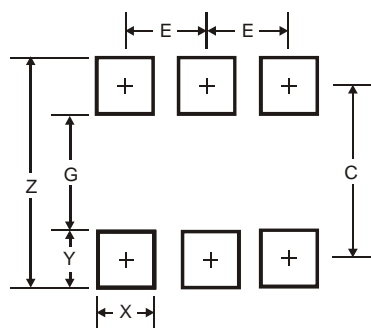
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C	1.7
E	0.5

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